

Application

The Series SKL is designed specifically for air cooling applications of Press Pack Disc Semiconductors like Diode, Thyristor, GTO and IGCT Modules.

General Characteristics

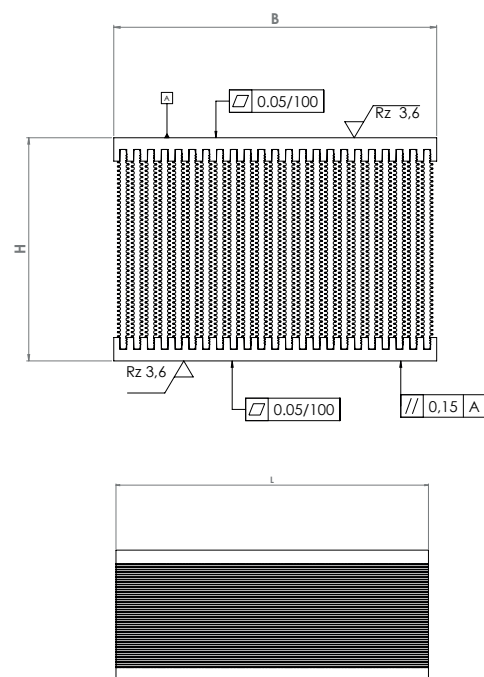
For Series SKL the fins will be assembled to the base plate by a special cold welding process instead of using thermal conductive glue. This assembling process ensures lowest thermal resistance between the base plate and the fins. That allows best heat transfer from the base plate to the fins.

Type	Width B mm	Height H mm	Length L max. mm	Number of Fins
SKL 64- L-45	300	45	300	50
SKL 116- L-45	116	45	300	50
SKL 152- L-75	152	75	300	80
SKL 201- L-105	201	105	300	100

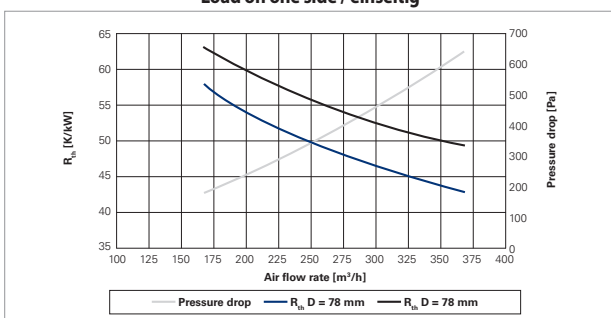
Surface finish / Oberflächenbehandlung:

- B= Blank / Blank
- N= Nicht plated / Vernickelt
- A= Anodized / Eloxiert
- C= Alodine / Chromatiert

Drawings



SKL - 152-180-105
Load on one side / einseitig



SKL - 152-180-105
Load on both side / zweiseitig

